Abstract

Designers who are only familiar with a research environment may have a difficult time adjusting in the industry. This major step is taken by most graduate students when they leave their familiar surroundings to pursue a professional career in a company like Texas Instruments. The objective of this seminar is to highlight some common industry practices, which are often unknown or not emphasized enough in a university environment. Several topics will be presented on how to: schedule a design effort, create effective schematics, floorplans and layouts; put together a solid design review presentation, debug a problem during testing, etc. In addition, several lessons learned will be reviewed which will highlight common industry practices such as failure analysis, yield improvement, etc. The material shown during this seminar should help prepare students to better understand what lies ahead and should also help them during job interviews. By the end of this presentation, students will realize that several of these techniques can be applied even in a research environment. Getting a "jump start" will make the transition from college to industry much easier.

Biography

Alexander H. Reyes received the M.S. and Ph.D. in Electrical Engineering from Texas A&M University in 1993 and 1999, respectively. He is the recipient of the 1996 IEEE Circuits & Systems Society Outstanding Young Author Award. Currently, he is the Basedband & Video Modules Manager in the Mixed Signal Wireless Group at Texas Instruments. His design team is responsible for the implementation of analog baseband and video designs for wireless applications. He also was promoted to the technical ladder for his contributions to revenue, developing top technical talent and influencing external decisions through technical innovations. Since he started at Texas Instruments, he has contributed to more than 20 projects. Among his designs are low-noise amplifiers, output drivers, A/D and D/A converters (traditional, delta-sigma, flash and current-steering), bandgaps, references, etc. He was the design leader of several projects that integrate audio baseband (Codec), power management and RF Codec modules on a single chip. Currently, he is the project leader for all video modules in the Wireless Group.

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